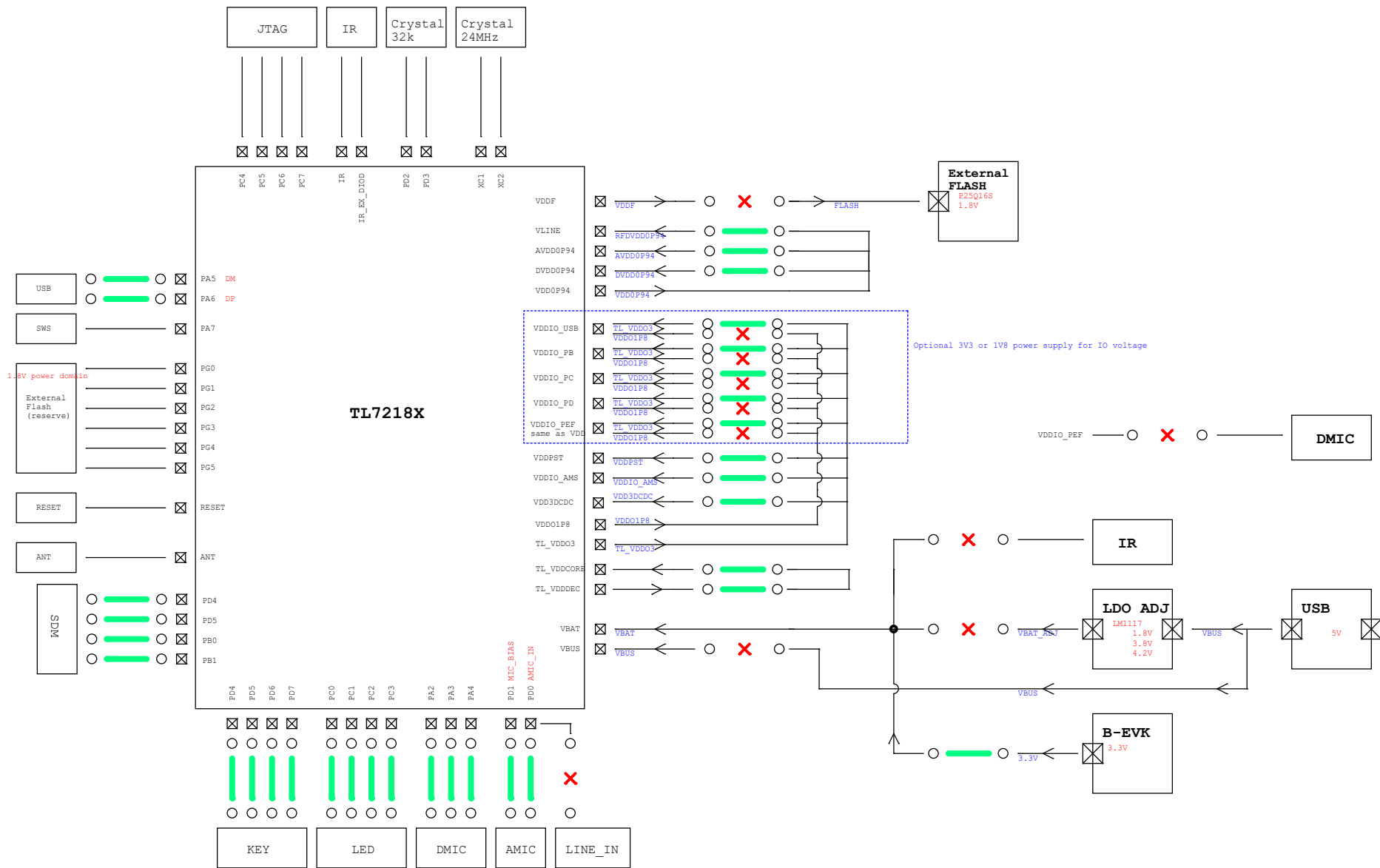
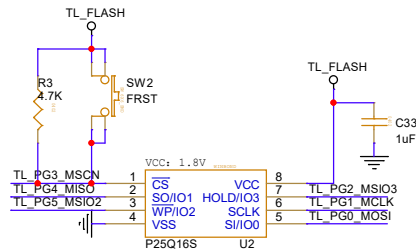


	Author	Approved by
	Dongtao	Xiang
	Date	Note
REV1.0	2023/12/07	Initial Version
REV1.1	2024/07/01	1. Update schematic symbol of 9258A. 2. Adjust the package of L2. 3. Remove external pull-up resistor of DP, will use internal resistor in chip. 4. Add the level shifter for SWS. 5. Correct DMIC power supply. 6. Optimize package and PCB layout for L2/C17/C36/C37. 7. Add R34/R35/R36/R37/R38. 8. Change J8 and J9's nets.
REV1.2	2024/09/03	1. Update schematic symbol of 9258A to 7218X. 2. Add SDM curcit
REV1.3	2025/01/06	1.Modify the level shifter's compatibility design. 2.Capacitors C8 and C9 are reversed; their positions should be swapped. 3.Add a small capacitor (1nF) on the DATA line. 4.Add an ESD protection component in the designated position.
REV1.4	2025/03/04	1.Add reserved positions for ESD devices and band-pass filter 2.Change the filter capacitor value at VLINE/Vbat/0P94 3.updata 7218X Footprint 4.DMIC data pin add 10nf cap 5.Change 32K crystal res to 0R and modify sws network 6.adjust PB and PD position 7.SDM circut add 33R 8.LED circut add separate power supply 9.Change 5V current limit resistor footprint to 0603,add 10uF cap and ESD
REV1.5	2025/05/23	1. modify PCB Layout

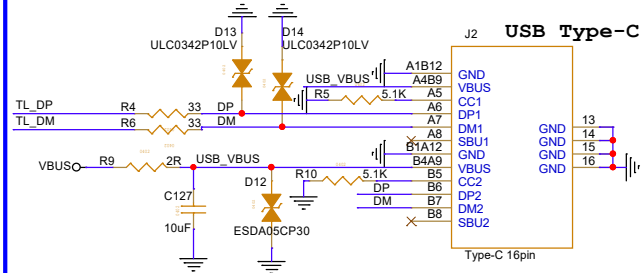


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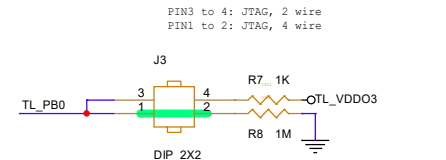
Flash_option



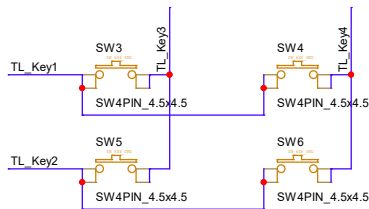
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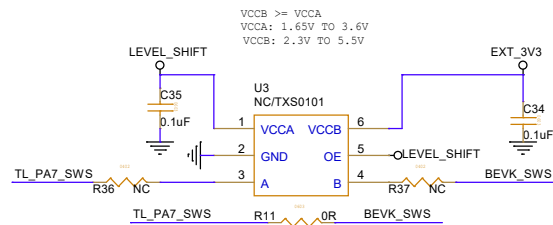
JTAG option



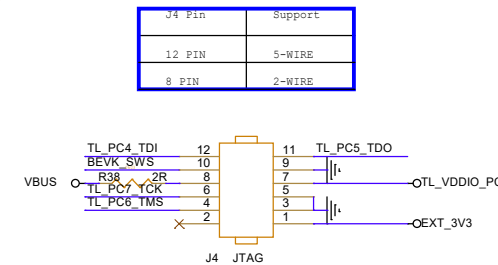
KEY



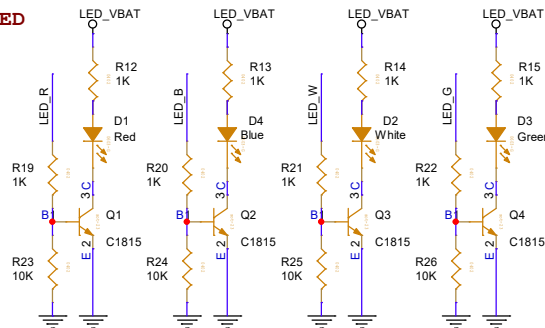
Level shift for SWS



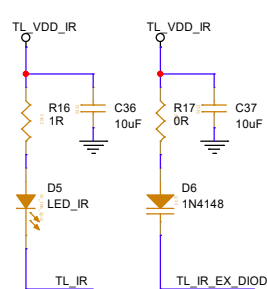
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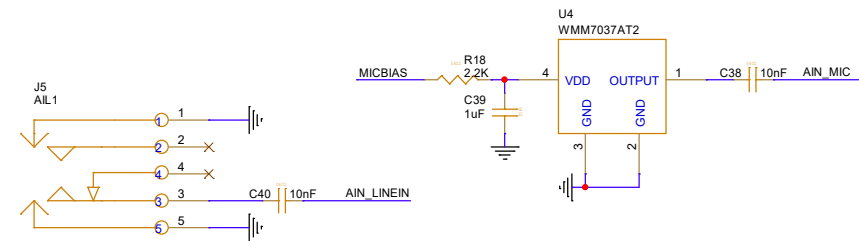
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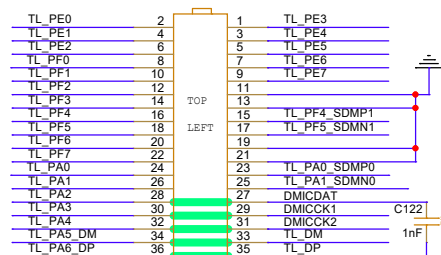
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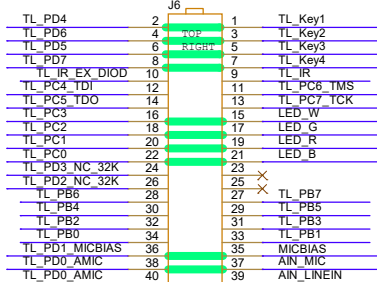
LINE IN & AMIC



J7

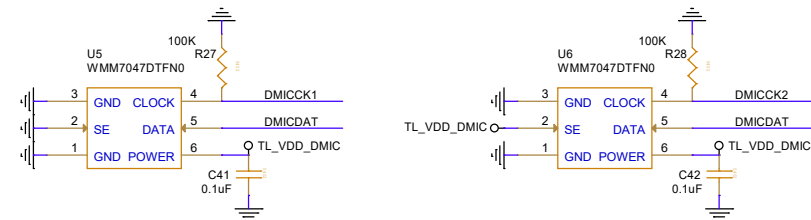


HEADER 18x2



HEADER 20x2

DMIC



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